

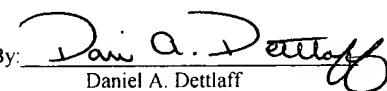


#10 AF/3723  
PATENT  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: RAEDER      Examiner: Nguyen, D.  
Serial No.: 09/383,876      Group Art Unit: 3723  
Filed: August 26, 1999      Docket No.: AMDA.316PA  
Title: POLISHING UNIFORMITY VIA PAD CONDITIONING

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this communication is being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on April 23, 2001.

By:   
Daniel A. Dettlaff

FINAL OFFICE ACTION RESPONSE

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated March 19, 2001, please consider the following remarks directed to the above-identified patent application:

Remarks

Favorable reconsideration of this application is requested in view of the following remarks. The Final Office Action dated March 19, 2001, indicated that claims 1-12 and 14-19 stand rejected under § 102(b) as being anticipated by *Renteln* (U.S. Patent No. 5,664,987). With respect to the § 102(b) rejection in view of *Renteln*, Applicant respectfully traverses and submits that the claimed invention is allowable over the cited reference for the reasons stated below.

Moreover, the Final Office Action failed to answer the substance of Applicant's previous arguments as required by MPEP §707.07(f). In specific regard, the Final Office Action did not point out anywhere in *Renteln* that identically discloses or describes determining that the wafer is being polished in a center-offset manner. Furthermore, the Final Office Action did not point out a teaching in *Renteln* that discloses positioning the wafer carrier misaligned with respect to the polishing pad. No support for either limitation has been provided. Withdrawal of the final

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